

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

Claim 1 (previously presented): An apparatus comprising:

a device chip including substrate and at least one circuit element fabricated on the substrate;

a cap over said device chip, said cap including a gasket having an inner surface and an outer surface;

a bonding agent bonding said cap to said device chip to define a hermetically sealed cavity; and

caulking agent at least partially surrounding said bonding agent to reinforce the hermetically sealed cavity, said caulking agent surrounding said bonding agent at least the inner surface of the gasket.

Claim 2 (original): The apparatus recited in claim 1 wherein the bonding agent comprises gold.

Claim 3 (original): The apparatus recited in claim 1 wherein the caulking agent is selected from a group consisting of amorphous fluorocarbon polymer, polyimide materials, and benzocyclobutene (BCB) based materials.

Claim 4 (original): The apparatus recited in claim 1 wherein the circuit element comprises a resonator.

Claim 5 (canceled).

Claim 6 (previously presented): The apparatus recited in claim 1 wherein the caulking agent surrounds at least a portion of the cap.

Claim 7 (canceled).

Claim 8 (canceled).

Claim 9 (original): The apparatus recited in claim 1 comprising multiple layers of the caulking agent.

Claim 10 (original): The apparatus recited in claim 9 wherein the multiple layers of the caulking agent comprises layers having different caulking material relative to other layers of the caulking agent.

Claim 11 (previously presented): The apparatus recited in claim 9 wherein the multiple layers of the caulking agent comprises layers having the same caulking material relative to other layers of the caulking agent.

Claims 12 to 19 (canceled).

Claim 20 (previously presented): The apparatus recited in claim 1 wherein the caulking agent surrounds said bonding agent at both the inner and the outer surfaces of the gasket.

Claim 21 (previously presented): The apparatus recited in claim 1 wherein the caulking agent extends from said cap to said device chip.

Claim 22 (previously presented): The apparatus recited in claim 1 wherein the caulking agent is adjacent to said bonding agent.

Claim 23 (previously presented): The apparatus recited in claim 1 wherein the caulking agent is separated from said bonding agent by open space prior to bonding said cap to said device chip.